

Vishay Siliconix

N-Channel 30-V (D-S) MOSFET

PRODUCT SUMMARY					
V _{DS} (V)	$R_{DS(on)}(\Omega)$	(Ω) I _D (A) ^a			
30	0.0035 at V _{GS} = 10 V	30	29 nC		
	0.0045 at $V_{GS} = 4.5 \text{ V}$	27	29110		

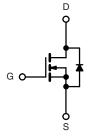
FEATURES

- · Halogen-free
- TrenchFET[®] Power MOSFET
- 100 % R_g Tested
- 100 % Avalanche Tested



APPLICATIONS

- Notebook PC Core
 - Low Side Switch



N-Channel MOSFET

		SO-8		
S	1		8	D
S	2		7	D
S	3		6	D
G	4		5	D
		Top View	l	

Ordering Information: Si4170DY-T1-GE3 (Lead (Pb)-free and Halogen-free)

Parameter		Symbol	Limit	Unit	
Drain-Source Voltage	V _{DS}	30	v		
Gate-Source Voltage		V_{GS}			± 20
Continuous Drain Current (T _J = 150 °C)	$T_{C} = 25 ^{\circ}\text{C}$ $T_{C} = 70 ^{\circ}\text{C}$ $T_{A} = 25 ^{\circ}\text{C}$ $T_{A} = 70 ^{\circ}\text{C}$	I _D	30 22.8 21.8 ^{b, c} 17.3 ^{b, c}	A	
Pulsed Drain Current		I _{DM}	70		
Continuous Source-Drain Diode Current	$T_{C} = 25 ^{\circ}C$ $T_{A} = 25 ^{\circ}C$	I _S	5.4 2.7 ^{b, c}		
Single Pulse Avalanche Current	L = 0.1 mH	I _{AS}	40		
Single Pulse Avalanche Energy		E _{AS}	80	mJ	
$ \begin{array}{c} T_{C} = \\ T_{C} = \\ T_{A} = \\ T_{A} = \end{array} $		P _D	6 3.3 3.0 ^{b, c} 1.9 ^{b, c}	w	
Operating Junction and Storage Temperature R	T _J , T _{stq}	- 55 to 150	°C		

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient ^{b, d}	t ≤ 10 s	R_{thJA}	33	42	°C/W	
Maximum Junction-to-Foot (Drain)	Steady State	R_{thJF}	16	21]	

Notes:

- a. Based on T_C = 25 °C.
- b. Surface Mounted on 1" x 1" FR4 board.
- c. t = 10 s.
- d. Maximum under Steady State conditions is 85 $^{\circ}\text{C/W}.$

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SPECIFICATIONS $T_J = 25 ^{\circ}\text{C}$ Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit	
Static				<u> </u>			
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} = 0 V, I _D = 250 μA	30			V	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$			33		mV/°C	
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I _D = 250 μA		- 6.4			
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	1.4		2.6	V	
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
		V _{DS} = 30 V, V _{GS} = 0 V			1		
Zero Gate Voltage Drain Current	IDSS	V _{DS} = 30 V, V _{GS} = 0 V, T _J = 55 °C			10	μΑ	
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	30			Α	
		V _{GS} = 10 V, I _D = 15 A		0.0029	0.0035	Ω	
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = 4.5 V, I _D = 10 A		0.0036	0.0045		
Forward Transconductance ^a	9 _{fs}	V _{DS} = 15 V, I _D = 15 A		90		S	
Dynamic ^b				<u> </u>			
Input Capacitance	C _{iss}			4355			
Output Capacitance	C _{oss}	V _{DS} = 15 V, V _{GS} = 0 V, f = 1 MHz		595		pF	
Reverse Transfer Capacitance	C _{rss}	30		256			
Total Gate Charge	Qg	V _{DS} = 15 V, V _{GS} = 10 V, I _D = 20 A		65	100	1	
		20 00 2		29	45	nC	
Gate-Source Charge	Q_{gs}	$V_{DS} = 15 \text{ V}, V_{GS} = 4.5 \text{ V}, I_D = 20 \text{ A}$		11.5			
Gate-Drain Charge	Q_{gd}			7.5			
Gate Resistance	R_{g}	f = 1 MHz	0.2	0.55	1.1	Ω	
Turn-On Delay Time	t _{d(on)}			15	30	ns	
Rise Time	t _r	$V_{DD} = 15 \text{ V}, R_L = 1.5 \Omega$ $I_D \cong 10 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 1 \Omega$		10	20		
Turn-Off Delay Time	t _{d(off)}			35	65		
Fall Time	t _f			8	16		
Turn-On Delay Time	t _{d(on)}			36	65		
Rise Time	t _r	$V_{DD} = 15 \text{ V}, R_{L} = 1.5 \Omega$		17	30		
Turn-Off Delay Time	t _{d(off)}	$I_D\cong 10 \text{ A}, V_{GEN}=4.5 \text{ V}, R_g=1 \Omega$		45	80		
Fall Time	t _f			20	40		
Drain-Source Body Diode Characteris	tics			•	'		
Continuous Source-Drain Diode Current	I _S	T _C = 25 °C			40	А	
Pulse Diode Forward Current ^a	I _{SM}				70		
Body Diode Voltage	V_{SD}	I _S = 3 A		0.74	1.1	V	
Body Diode Reverse Recovery Time	t _{rr}			34	65	ns	
Body Diode Reverse Recovery Charge	Q _{rr}	L_ = 10 A dl/dt = 100 A/vo T = 25 °C		29	55	nC	
Reverse Recovery Fall Time	t _a	$I_F = 10 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 ^{\circ}\text{C}$		17		ns	
Reverse Recovery Rise Time	t _b			17			

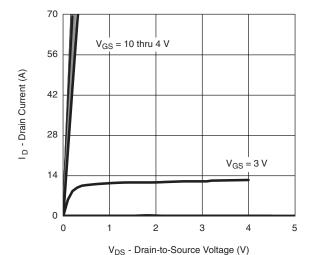
- a. Pulse test; pulse width \leq 300 μ s, duty cycle \leq 2 %.
- b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



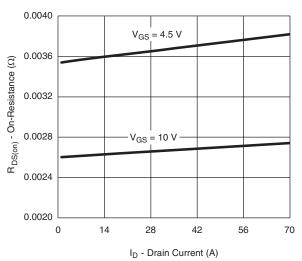
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TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

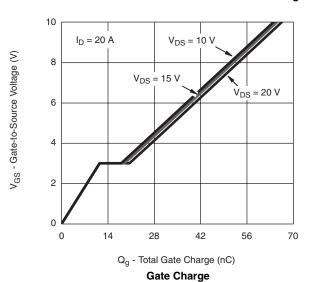


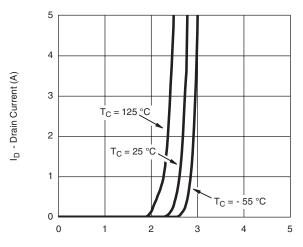
VDS - Diain-to-Source voltage (V





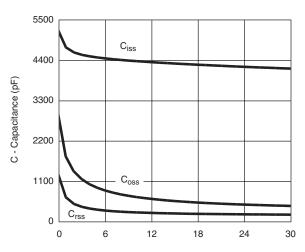
On-Resistance vs. Drain Current and Gate Voltage





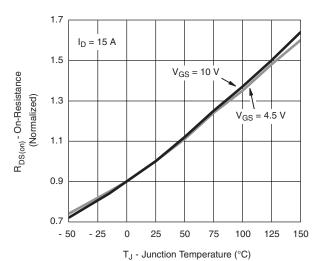
V_{GS} - Gate-to-Source Voltage (V)

Transfer Characteristics



V_{DS} - Drain-to-Source Voltage (V)

Capacitance

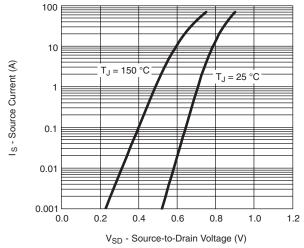


On-Resistance vs. Junction Temperature

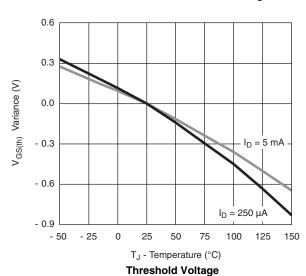
Si4170DY

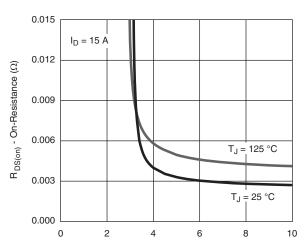
Vishay Siliconix

TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

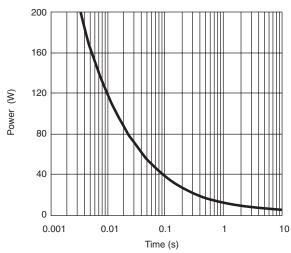


Source-Drain Diode Forward Voltage

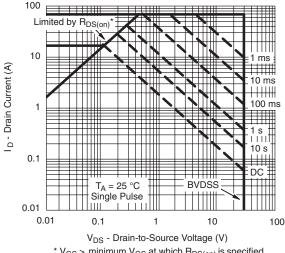




V_{GS} - Gate-to-Source Voltage (V) On-Resistance vs. Gate-to-Source Voltage



Single Pulse Power, Junction-to-Ambient



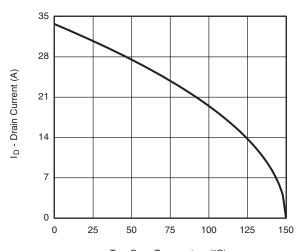
* V_{GS} > minimum V_{GS} at which $R_{DS(on)}$ is specified

Safe Operating Area, Junction-to-Ambient



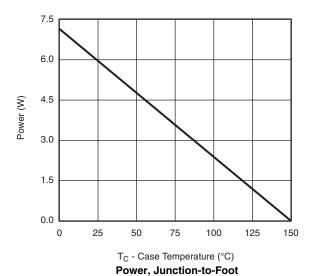
Si4170DY Vishay Siliconix

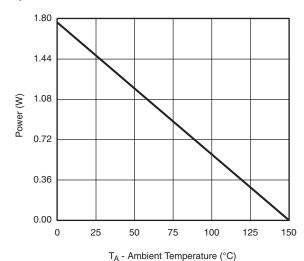
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



T_C - Case Temperature (°C)

Current Derating*





Power, Junction-to-Ambient

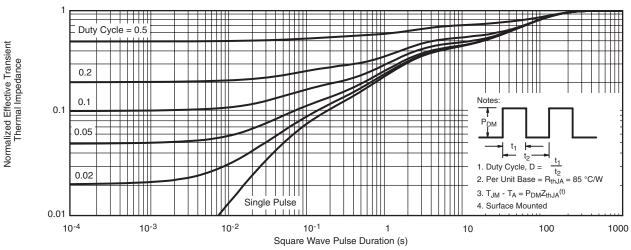
^{*} The power dissipation P_D is based on $T_{J(max)}$ = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

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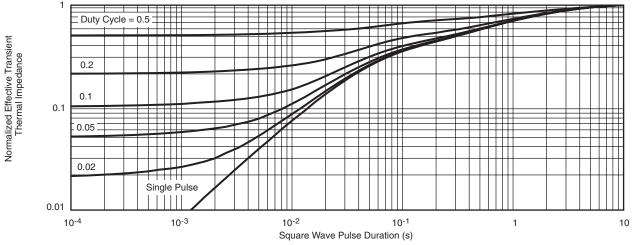
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TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Foot

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